Surface Technology Systems (STS) Multiplex Reactive Ion Etcher (RIE)

INCLUDES: load lock, PC-controlled RIE process chamber, power distribution cabinet, RF trolley, remote gas box, and chiller.

CONFIGURATION:

- Load Lock System: Wafer size from 3 inch to 8 inch (75mm to 200mm) capable; Wafer set size = 6 inch (150mm); requires Leybold Ecodry L rotary pump or equivalent (not included).
- RIE Process Module: MESC RIE SC100M process chamber; version 1.0; PC controlled; Intellimetrics end-point detector (EPD); Electrode temperature control (+5 to +40 deg C); non-clamped electrode; ENI ACG3B 300/30 watt (13.56MHz) RF supply & matching unit; Remote gasbox; requires Leybold Dryvac 50S dry pump or equivalent (not included)
- Electrode Cooling: Huber Unistat 140 chiller
- Gasbox: Remote R/H (standard-inc 2x PFC1 module); Gasses: (1) O2, (2) Ar, (3) CF4, (4) SF6.